

#### **Features**

- Low R<sub>DS(on)</sub> & FOM
- · Extremely Low Switching Loss
- · Excellent Stability and Uniformity
- · Fast Switching and Soft Recovery
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)
- Halogen Free Available Upon Request By Adding Suffix "-HF"
- · Epoxy Meets UL 94 V-0 Flammability Rating
- · Moisture Sensitivity Level 1

# **Maximum Ratings**

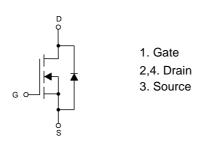
- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 62°C/W Junction to Ambient<sup>(1)</sup>
- Thermal Resistance: 0.65°C/W Junction to Case

Parameter	Symbol	Value
Drain-Source Voltage	$V_{DS}$	100V
Gate-Source Volltage	$V_{GS}$	±20V
Continuous Drain Current <sup>(2)</sup> ,T <sub>C</sub> =25°C	I <sub>D</sub>	130A
Pulsed Drain Current <sup>(3)</sup> , T <sub>C</sub> =25°C	I <sub>D,pluse</sub>	390A
Power Dissipation <sup>(4)</sup> , T <sub>C</sub> =25°C	P <sub>D</sub>	192W
Single Pulsed Avalanche Energy <sup>(5)</sup>	E <sub>AS</sub>	500mJ

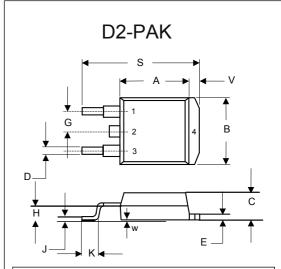
## Note:

- 1. The Value of  $R_{\theta,JA}$  is Measured with the Device Mounted on 1 in<sup>2</sup> FR-4 Board with 2oz. Copper, In a Still Air Environment with  $T_A$ =25°C.
- 2. Calculated Continuous Current Based on Maximum Allowable Junction Temperature.
- 3. Repetitive Rating: Pulse Width Limited By Max. Junction Temperature.
- 4. Pd is Based on Max. Junction Temperature, Using Junction-Case Thermal Resistance.
- 5.  $V_{DD}$ =50V,  $R_G$ =25 $\Omega$ , L=0.5mH, Starting  $T_J$ =25 $^{\circ}$ C.

#### **Internal Structure**

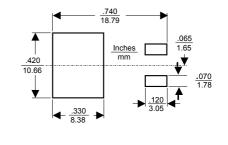


# N-Channel MOSFET



DIMENSIONS						
DIM	INCHES		MM		NOTE	
DIIVI	MIN	MAX	MIN	MAX	NOTE	
Α	0.320	0.359	8.13	9.14		
В	0.380	0.411	9.65	10.45		
С	0.160	0.190	4.06	4.83		
D	0.020	0.035	0.51	0.89		
Е	0.045	0.055	1.14	1.40		
G	0.083	0.105	2.10	2.67		
Н	0.096	0.134	2.43	3.40		
J	0.014	0.021	0.35	0.53		
K	0.090	0.131	2.29	3.32		
S	0.575	0.625	14.22	16.22		
V	0.045	0.055	1.14	1.40		
W	0.000	0.006	0.00	0.15		

### Suggested Solder Pad Layout

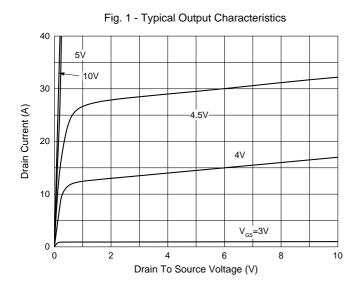


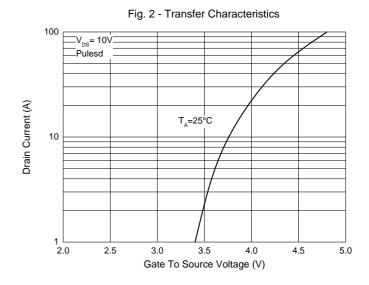


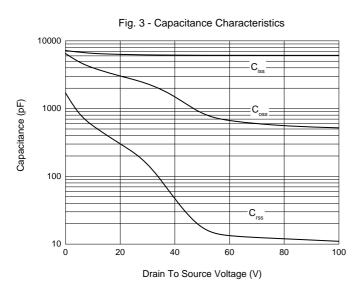
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Static Characteristics			l			
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100			V
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	2		4	V
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V			1	μA
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =60A		4.0	4.6	mΩ
Dynamic Characteristics						
Drain-Source On-Voltage	C <sub>iss</sub>			6124.6		pF
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> =0V,V <sub>DS</sub> =50V,f=1MHz		792.3		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			15.1		pF
Turn-On Delay Time	t <sub>d(on)</sub>			28.2		ns
Rise Time	t <sub>r</sub>	$V_{GS}$ =10V, $V_{DS}$ =50V, $R_{G}$ =2.2 $\Omega$ , $I_{D}$ =22 A		7.5		ns
Turn-Off Delay Time	t <sub>d(off)</sub>			81.9		ns
Fall Time	t <sub>f</sub>			20.1		ns
Gate Charge Characteristics			I	.1		
Total Gate Charge	Qg			101.6		nC
Gate-Source Charge	Q <sub>gs</sub>	I <sub>D</sub> =22A,V <sub>DS</sub> =50V,V <sub>GS</sub> =10V		20.6		nC
Gate-Drain Charge	Q <sub>gd</sub>	1D-22A, VDS-30V, VGS-10V		28.7		nC
Gate Plateau Voltage	V <sub>plateau</sub>			4.2		V
<b>Body Diode Characteristics</b>				•		•
Diode Forward Current	Is	V N			130	Α
Pulsed Source Current	I <sub>SP</sub>	$V_{GS}$ < $V_{th}$			390	Α
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =20A, V <sub>GS</sub> =0V			1.3	V
Reverse Recovery Time	t <sub>rr</sub>			82.1		ns
Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>S</sub> =10A,di/dt=100A/μs		248.4		nC
Peak Reverse Recovery Current	I <sub>rrm</sub>			4.9		Α

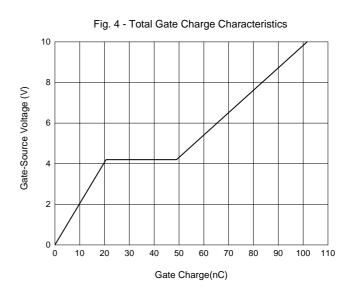


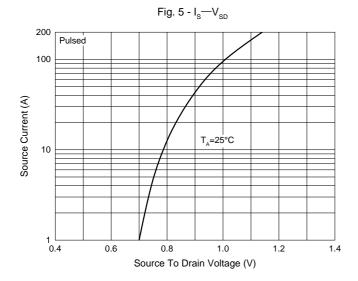
## **Curve Characteristics**

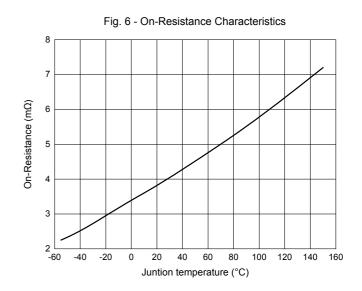














# **Ordering Information**

Device	Packing	
Part Number-TP	Tape&Reel: 800pcs/Reel	
Part Number-BP	Tube: 5Kpcs/Ctn	

Note: Adding "-HF" Suffix For Halogen Free, eg. Part Number-TP-HF

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